

SOT1652-3 FBGA780, plastic, fine-pitch ball grid array; 780 bumps; 0.8 mm pitch; 23 mm x 23 mm x 1.92 mm body 26 February 2019 Package information

Package information

#### **Package summary** 1

Terminal position code	B (bottom)
Package type descriptive code	FBGA780
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-01-2016
Manufacturer package code	98ASA00659D

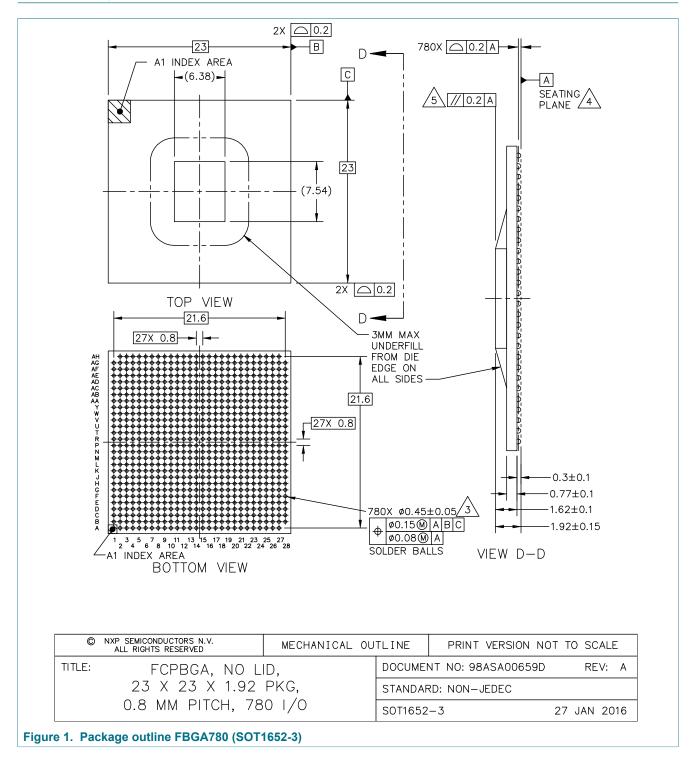
#### Table 1. Package summary

Parameter	Min	Nom	Мах	Unit
package length	-	23	-	mm
package width	-	23	-	mm
seated height	-	1.92	2.07	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	780	-	



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## 2 Package outline



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NOTES:

	NOTES:				
	1. ALL DIMENSIONS IN MILLIME	TERS.			
	2. DIMENSIONING AND TOLERA	NCING PER ASME Y14	.5M—1994.		
/	3. MAXIMUM SOLDER BALL DIA	METER MEASURED PA	RALLEL TO	DATUM A.	
Z	4. DATUM A, THE SEATING PL SOLDER BALLS.				THE
Z	5. PARALLELISM MEASUREMEN OF PACKAGE.	T SHALL EXCLUDE AN	Y EFFECT (	DF MARK ON TOP SUF	RFACE
©	NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OU	TLINE	PRINT VERSION N	OT TO SCALE
TITLE:	FCPBGA, NO LI		DOCUMEN	IT NO: 98ASA00659E	REV: A
	23 X 23 X 1.92		STANDAR	D: NON-JEDEC	
	0.8 MM PITCH, 78	0 1/0	SOT1652-	_ 3	27 JAN 2016

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### 3 Legal information

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